

2SC4212

Silicon NPN triple diffusion planar type

For color TV horizontal deflection driver

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

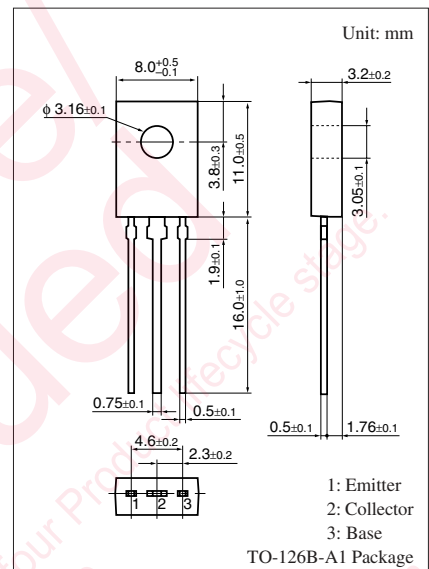
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	350	V
Collector-emitter voltage (Base open)	V_{CEO}	300	V
Emitter-base voltage (Collector open)	V_{EBO}	7.5	V
Collector current	I_C	200	mA
Peak collector current	I_{CP}	400	mA
Collector power dissipation	P_C	1.2 5.0 *	W
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

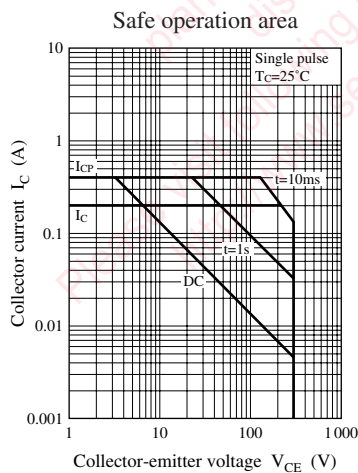
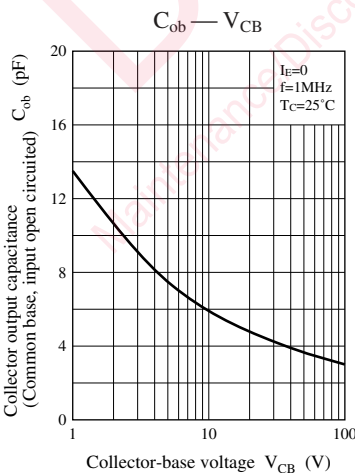
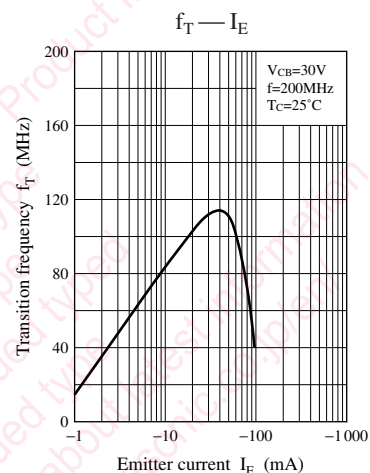
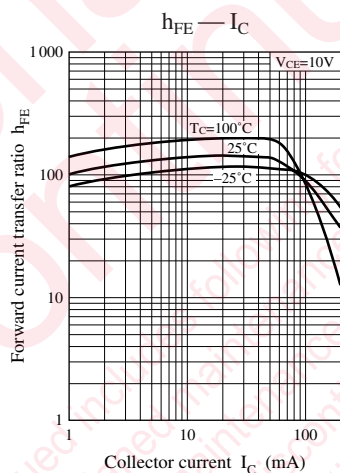
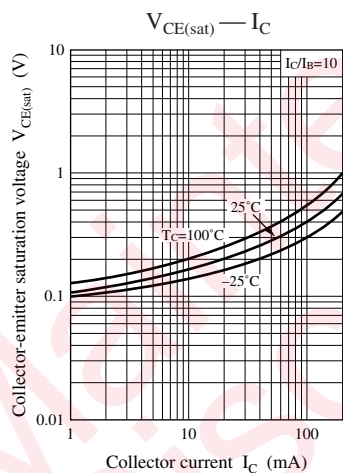
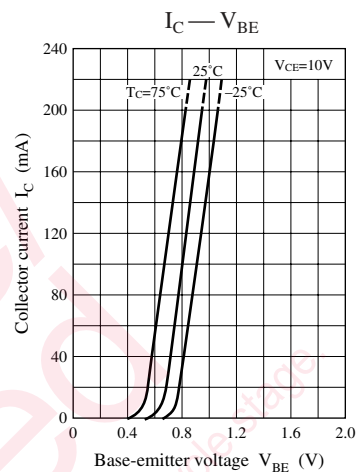
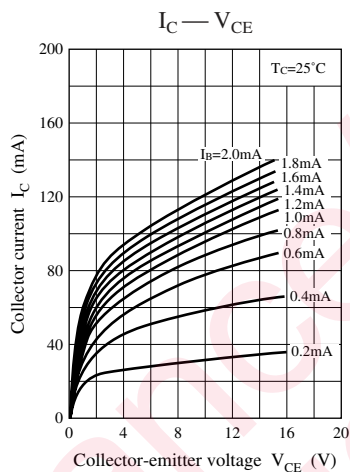
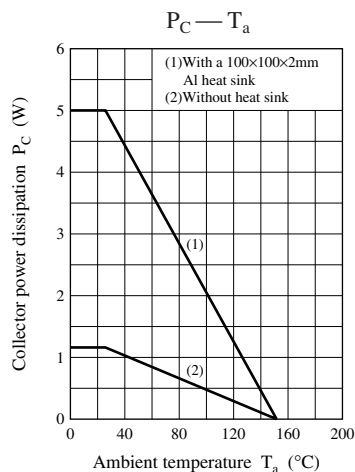
Note) *: With a $100 \times 100 \times 2$ mm Al heat sink

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 100 \mu\text{A}$, $I_E = 0$	350			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 5 \text{ mA}$, $I_B = 0$	300			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 100 \mu\text{A}$, $I_C = 0$	7.5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 200 \text{ V}$, $I_E = 0$			2	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 5 \text{ V}$, $I_C = 0$			2	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = 10 \text{ V}$, $I_C = 10 \text{ mA}$	40		250	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 50 \text{ mA}$, $I_B = 5 \text{ mA}$			1	V
Transition frequency	f_T	$V_{CB} = 30 \text{ V}$, $I_E = -10 \text{ mA}$, $f = 200 \text{ MHz}$	50	80		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = 50 \text{ V}$, $I_E = 0$, $f = 1 \text{ MHz}$			4.5	pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.





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